

Inspection of bonding spots status from semi-manufactured SD card

Application: Inspection of bonding spots status from semi-manufactured SD card
Check if the bonding spots are welding together

NEW TRY Products: Telecentric lens(VCM230-26) + Ring light

- C/F Mount Bi telecentricity;
- <0.1% distortion;
- High contrast;
- Clear imaging on the target area.

Camera: 5MP Basler-piA-2400-12gm, 2/3", 3.45um

- Resolution: Up to 2456*2058 pixels.

Test conclusion:

- Accuracy: Depending on different cameras resolution and image areas.
19.34mm × 16.21mm <0.007mm with 2456x2058 pixels.
- Performance: Clear target imaging with high contrast makes it easy to proceed inspection.
- Test image: Achieved image with high definition and great homogeneity.

